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Amdt
J. McMillan
11/26/02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

	Pan et al.	Docket No.:	TI-31192
Serial No.:	09/998,606	Examiner:	Nguyen, C.
Filed:	11/30/01	Art Unit:	2811
For:	HIGH DENSITY CAPACITOR USING TOPOGRAPHIC SURFACE		

Amendment under 37 CFR 1.115

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Assistant Commissioner of Patents
Washington, DC 20231

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 06/26/02. They are respectfully submitted as a full and complete response to that Action.

Please amend the above-referenced application as follows:

In the Claims:

Cancel claims 1-17, claims 11-17 being drawn to a non-elected invention.

Please add the following claims:

--18. An integrated circuit having an analog circuit stage, comprising:

a semiconductor layer having a plurality of recesses formed therein;

a dielectric layer over said semiconductor layer including within said plurality of recesses; and

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CERTIFICATION OF FACSIMILE TRANSMISSION

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FACSIMILE COVER SHEET

X FACSIMILE COVER SHEET	X AMENDMENT (4 Pages)
___ NEW APPLICATION	X EOT 2mth (3 Pages)
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___ ASSIGNMENT (# Pages)	___ APPEAL (# Pages)
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___ INFORMAL DRAWINGS	___ REPLY BRIEF (IN TRIPLICATE) (# Pages)
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___ DIVISIONAL APP'N	

NAME OF INVENTOR(S): Pan	RECEIPT DATE & SERIAL NO.: **Serial No.: 09/998,606** **Filing Date:** 11/30/2001
TITLE OF INVENTION: High Density Capacitor Using Topographic . . .	
TI FILE NO.: TI-31192 / DEPOSIT ACCT. NO.: **20-0668**	
FAXED: November 22, 2002 DUE: 9/26/2002 ATTY/SEC'Y: JJG	

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